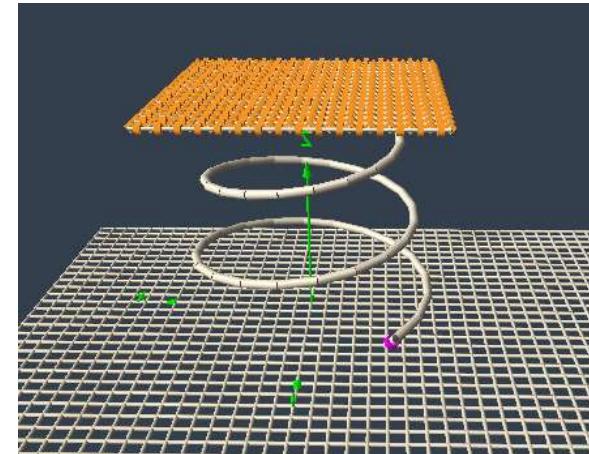
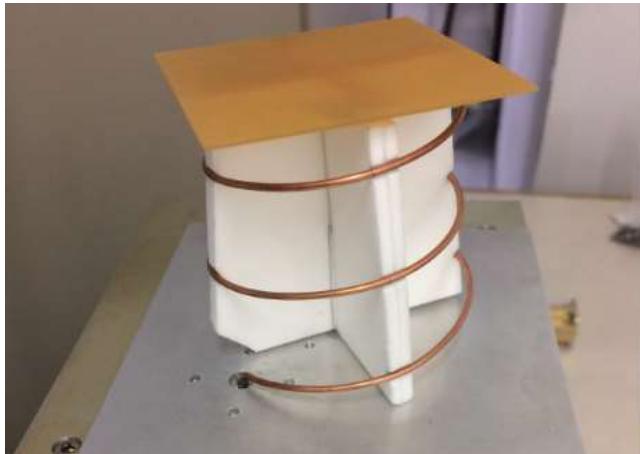


DIELECTRIC FILMS IN NEC2

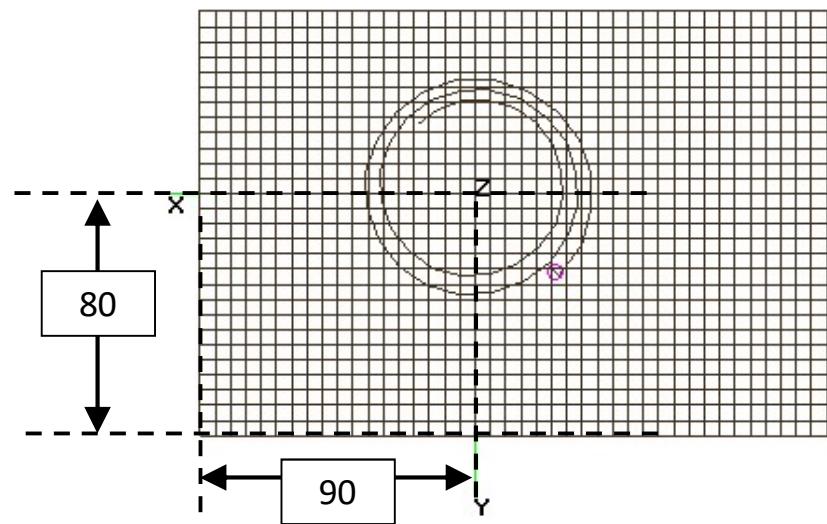
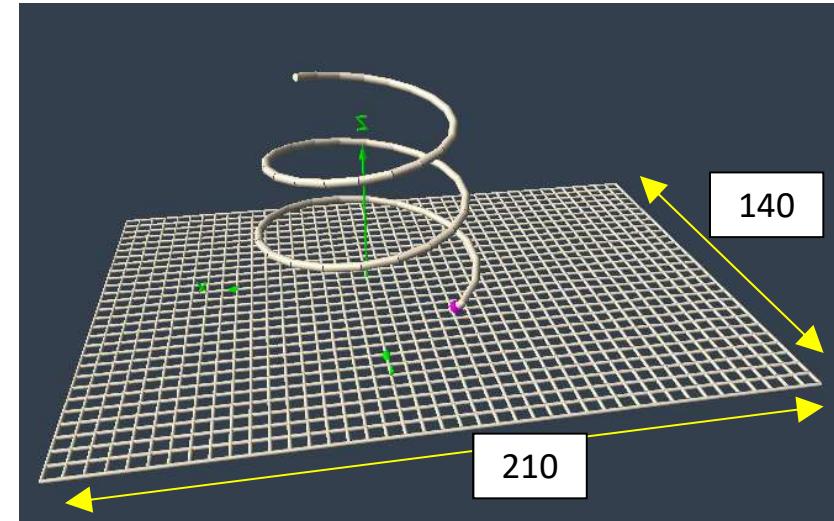
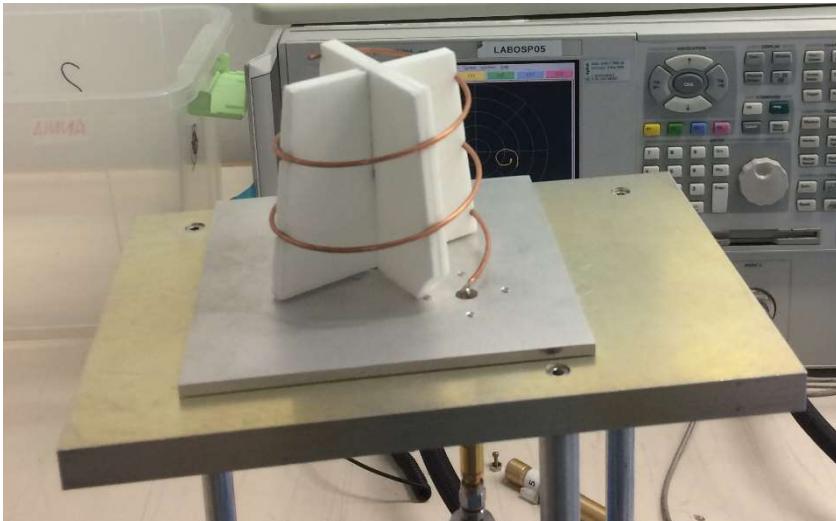
“The use of dielectrics in NEC2 is not allowed”. This is a general topic.

However, this presentation shows how to overcome this limitation in case of dielectric thin films. A film is considered thin if their thickness is $< \lambda d/10$. Where λd is the wavelength in the dielectric media.

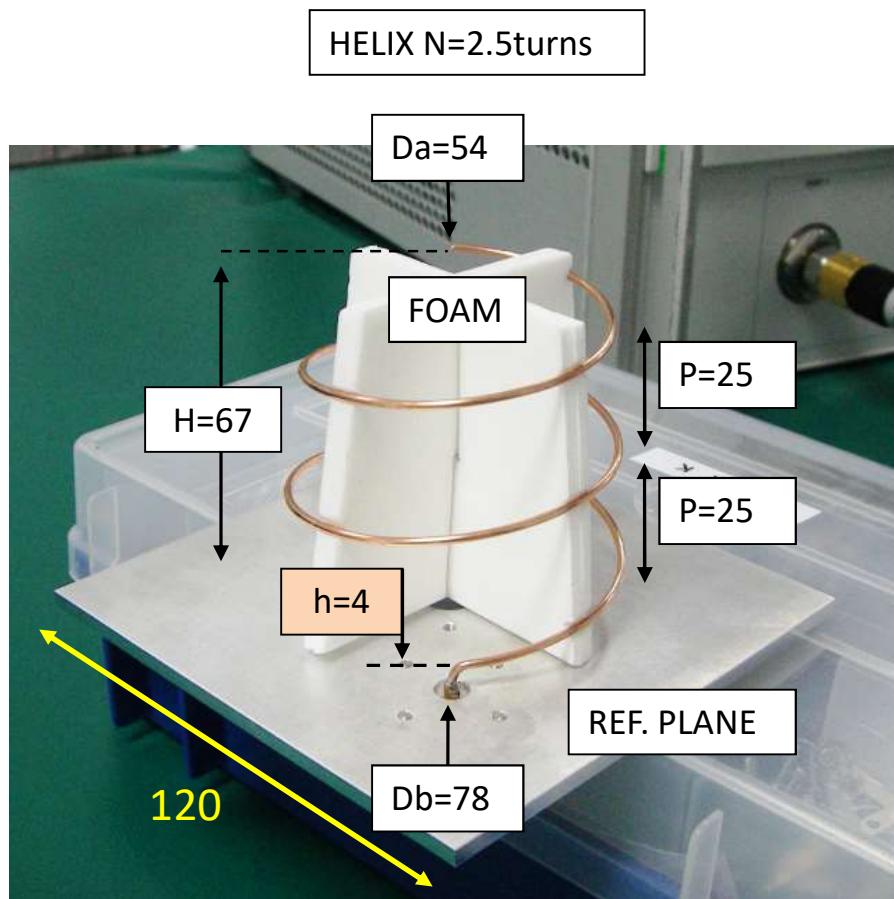
**PHYSICAL MODEL (Left) and 4NEC2 MODEL (right)
of an helix plus dielectric sheet**



PHYSICAL MODEL AND 4NEC2 MODEL OF HELIX



HELIX GEOMETRY



Da = Diameter at base
Db = Diameter at top

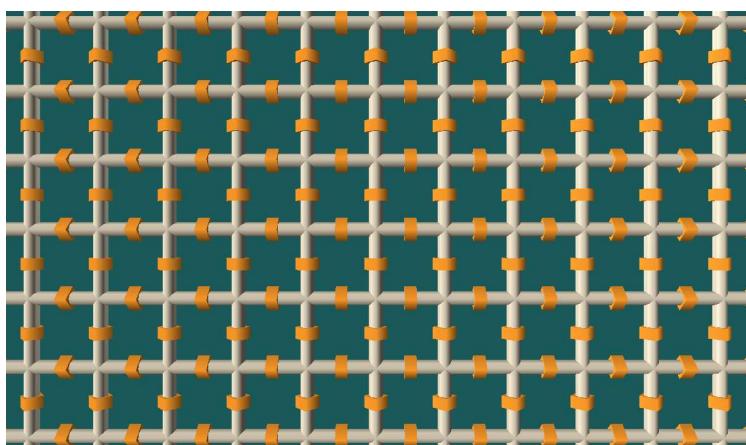
MODELING OF DIELECTRIC FILM

The dielectric plate (80 x 80mm) is modeled by a grid of 17 wires in X-direction and 17 wires in Y-direction. Each wire has 16 segments. Each segment is capacitive loaded by CD (LD CARD option 1)

```
LD 1 1 1 16 0 0 CAPD
```



This CARD loads the 16 segments of wire (Tag=1)



- T Thickness of dielectric film
- Δ_x Grid segment length (x)
- Δ_y Grid segment length (y)
- ϵ_0 8.85 e-12 (F/m)
- ϵ' Relative dielectric constant

$$CD_x = \epsilon_0(\epsilon' - 1) \frac{T * \Delta_x}{\Delta_y} \quad (\text{F}/\square)$$

Capacitance loading in x-direction.

If $\Delta_x = \Delta_y = \Delta$ then, $CD_x = CD_y = CD$ (isotropic material)

$$CD = \epsilon_0 * (\epsilon' - 1) * T \quad (F/\square)$$

T Thickness of dielectric film in meters ($< \lambda/10$)

$\epsilon_0 = 8.85 \text{ e-12 } (F/m)$

ϵ' is the relative dielectric constant

CD (in Farads) is independent of grid density ($T < \lambda/10$ and $\Delta < \lambda/10$)

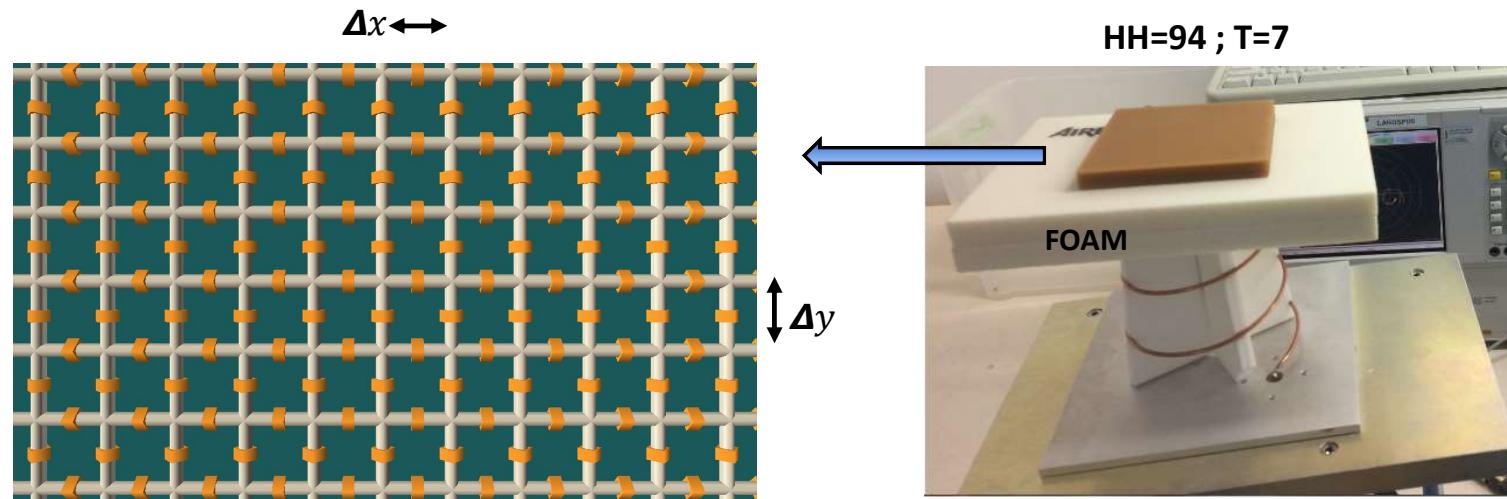
Figures of pages 9 and 10 shows effectively that the results at 1600 MHz are the same modeling the same dielectric plate with $\Delta = 5\text{mm}$ or with $\Delta = 3.2\text{mm}$ and using the same value of CD.

Figures in pages 17 and 18 shows that the results are the same for different thickness of dielectric plate if the product $(\epsilon' - 1) * T$ is constant.

Non isotropic dielectric materials can also be analyzed. $\Delta_x \neq \Delta_y$

By experimental adjust of Cd to 2e-13 F/□, with a thickness plate of T=7 mm, the relative dielectric constant is estimated. Measured foam effects are negligible.

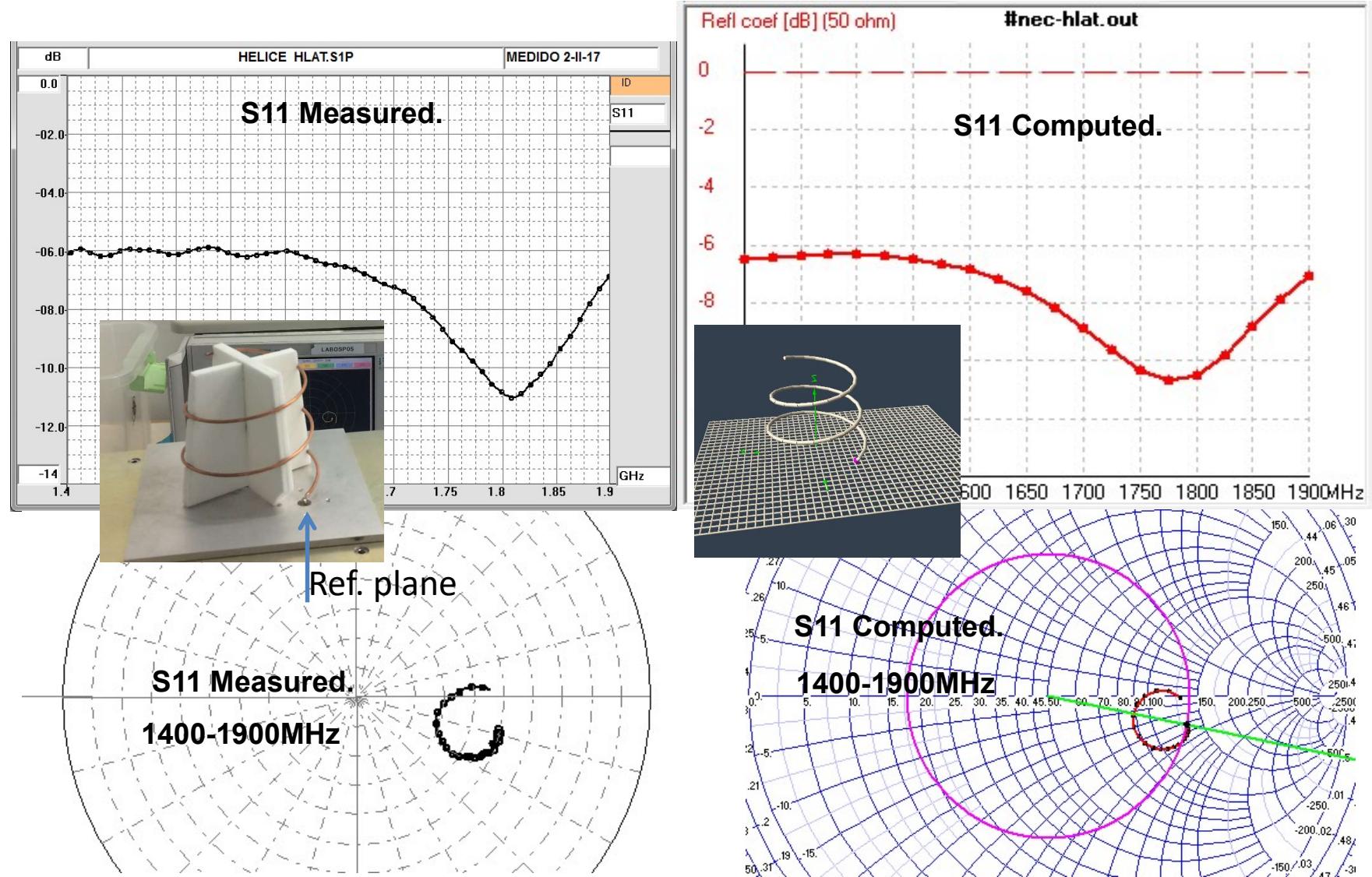
HH is distance of dielectric (at middle) to helix ground plane.



$$Cd_x = \epsilon_0 (\epsilon' - 1) \frac{T * \Delta_x}{\Delta_y} \quad (\text{F/}\square) \quad \Delta_x = \Delta_y = 5\text{mm}$$

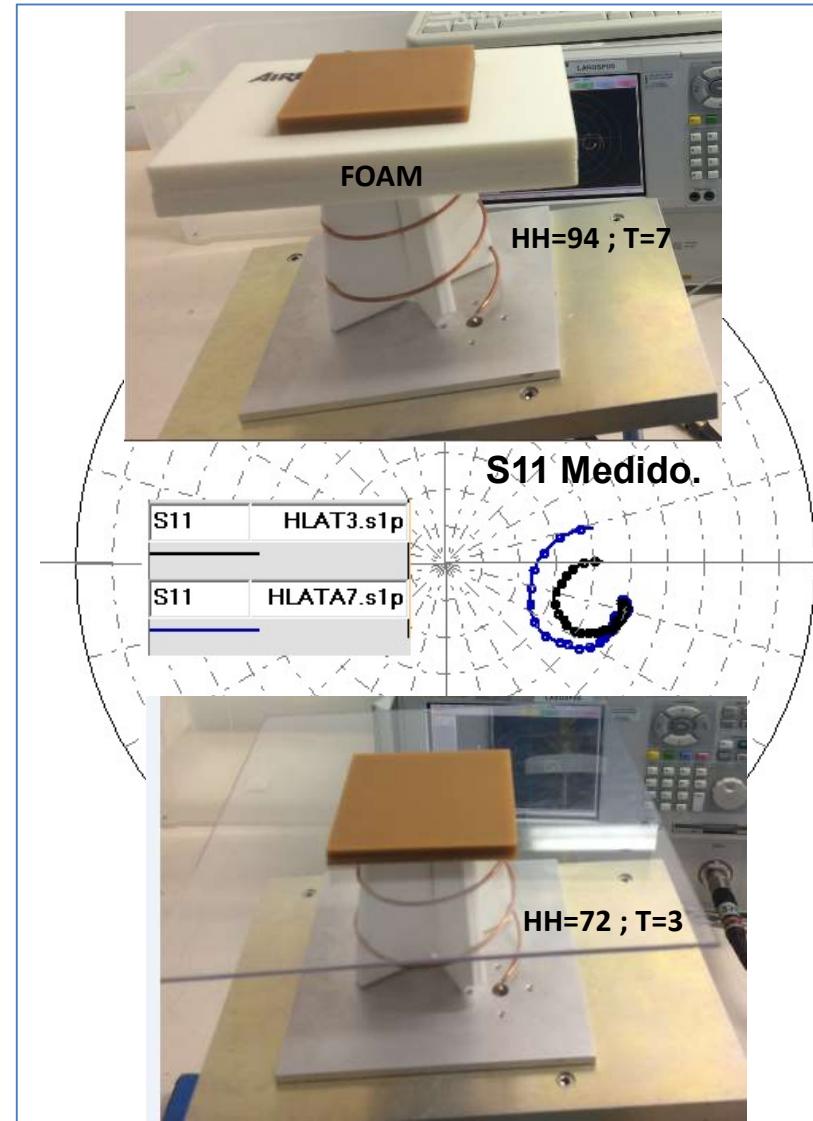
$$2e-13 = (0.885 e-11) * (\epsilon' - 1) * 7e-3 \\ \epsilon' = 4.2 \text{ (Estimated)}$$

HELIX ALONE : S11 MEASURED (left) & COMPUTED NEC (right)

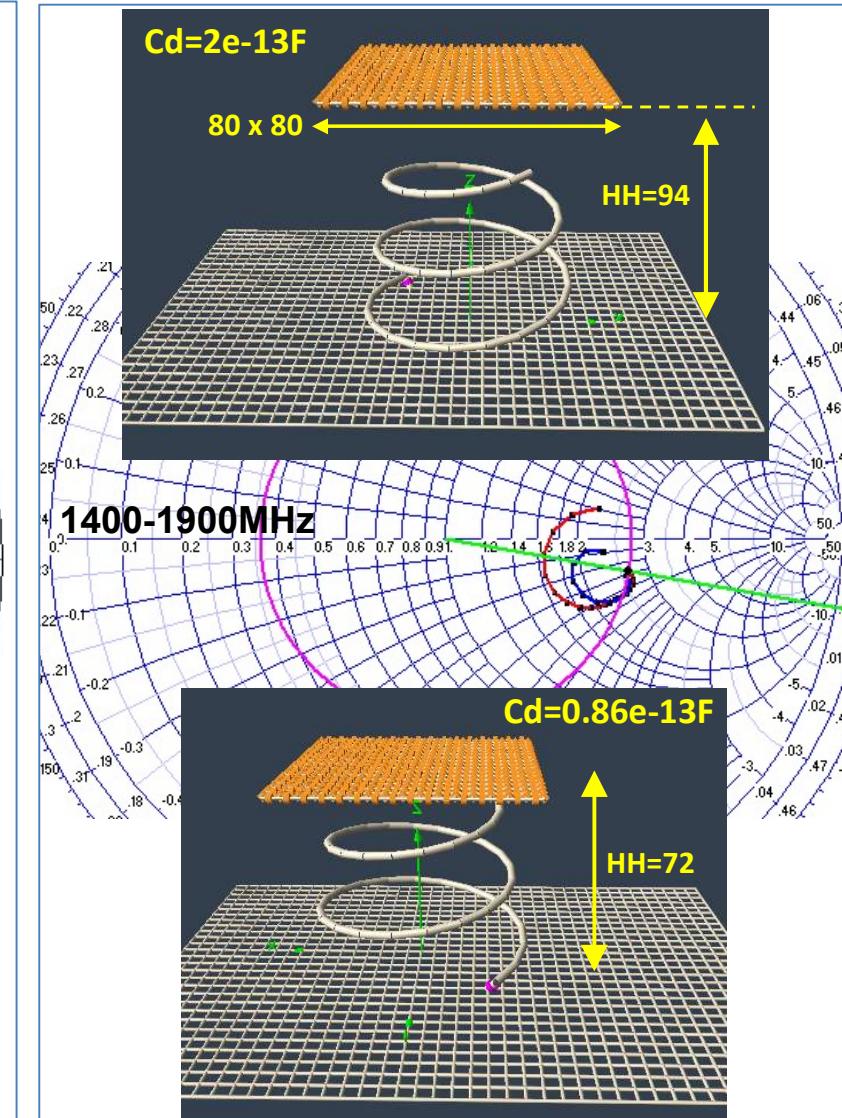


HELIX PLUS DIELECTRIC PLATE (T=7mm) VERSUS HH

MEASURED (S11)

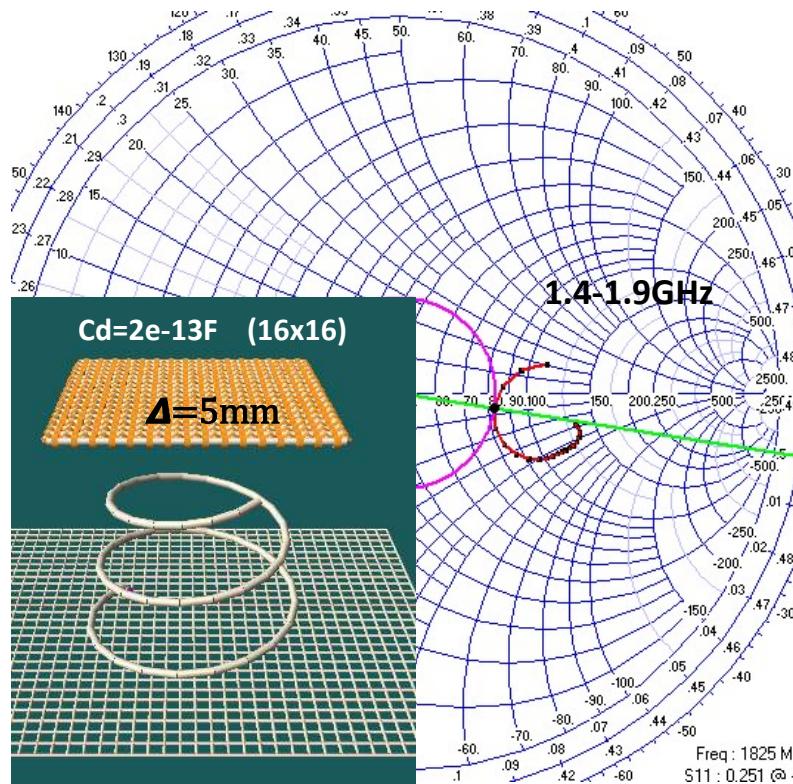


Nec-HLATA6_.NEC

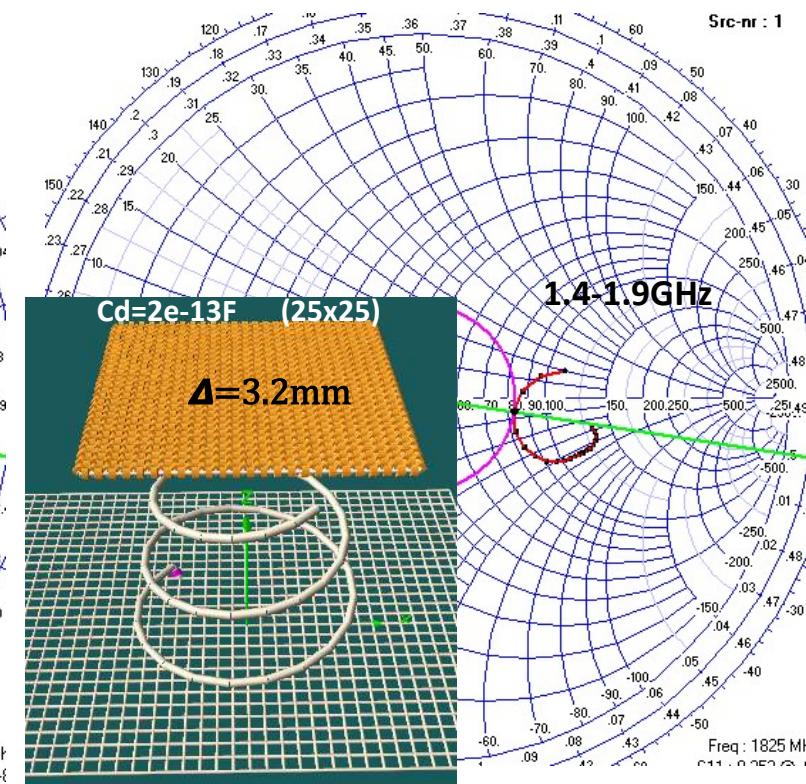


S11 VERSUS DIFERENT GRID MESHING (4NEC2)

nec-HLATA6.out



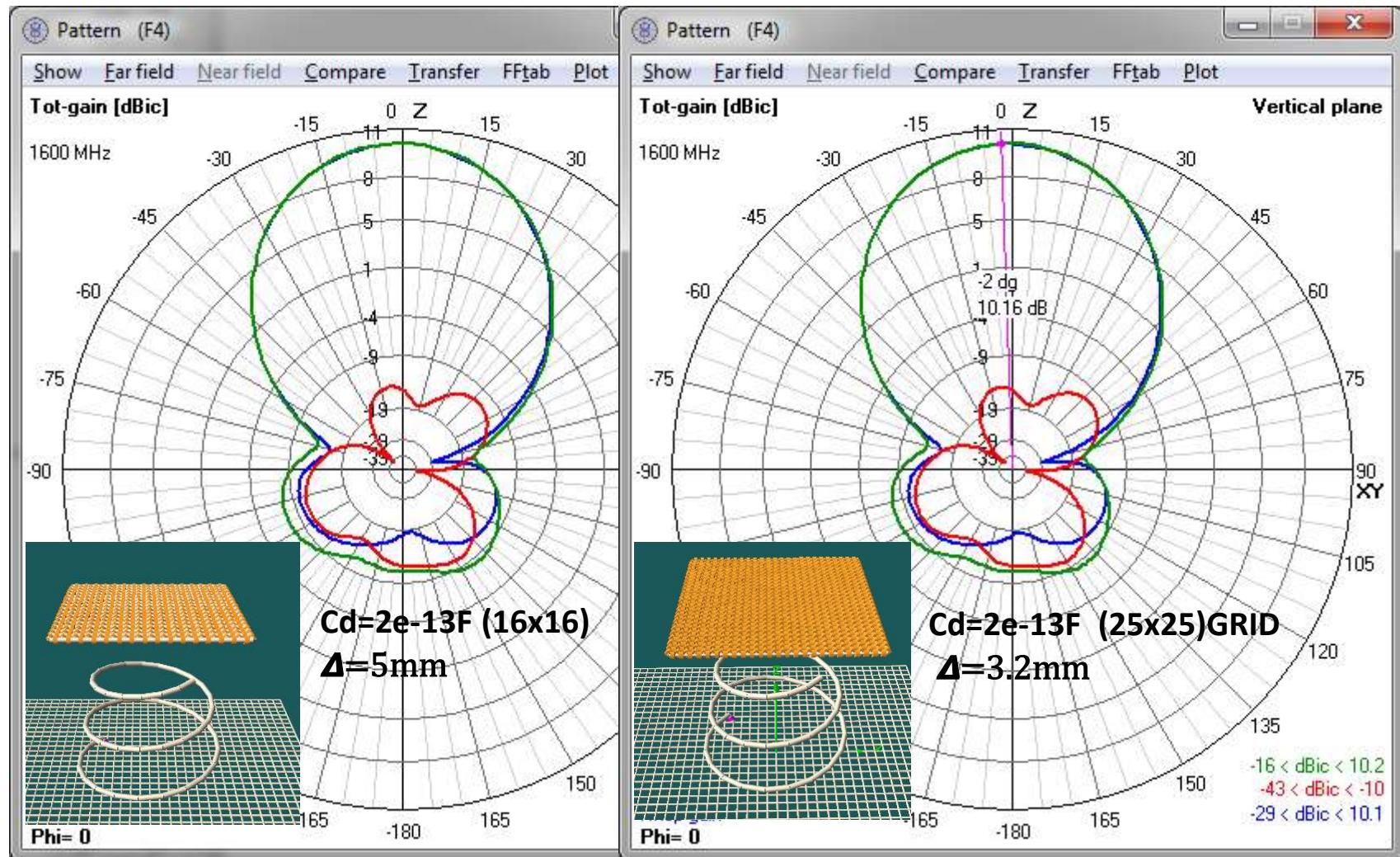
nec-HLATJ6.out



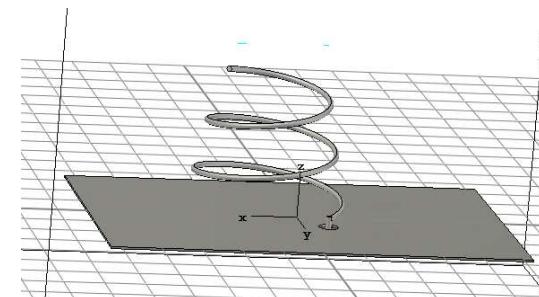
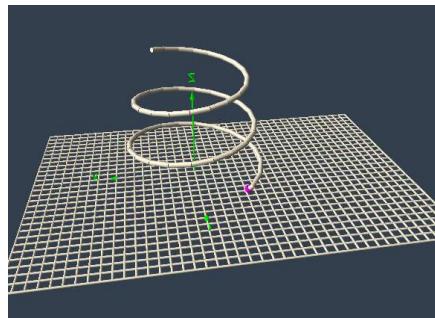
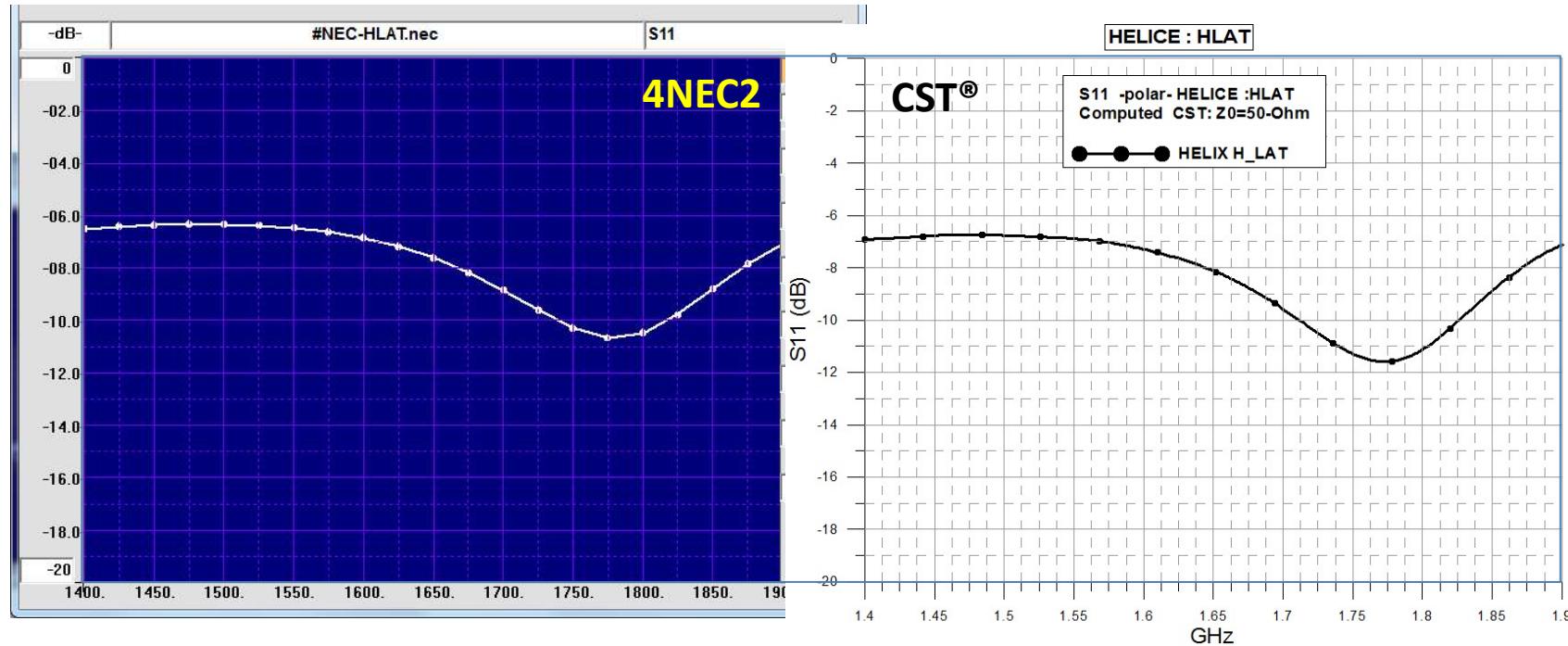
$$Cd_x = \epsilon_0(\epsilon' - 1) \frac{T * \Delta_x}{\Delta_y} \quad (\text{F}/\square)$$

T thickness of dielectric film
 Δ_x grid segment length (x)
 Δ_y grid segment length (y)
 ϵ_0 8.85 e-12 (F/m)

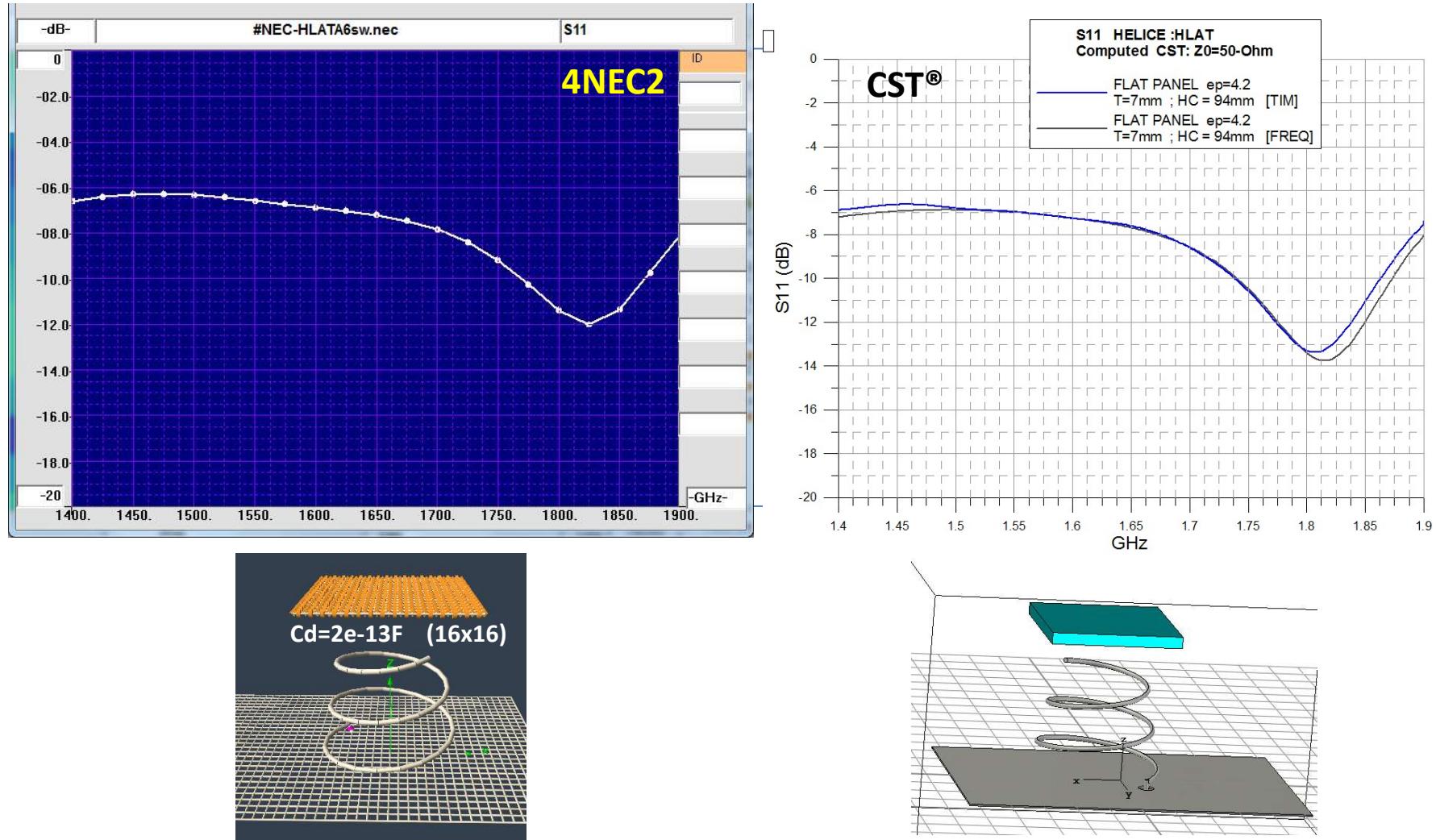
PATTERN CUT VERSUS DIFERENT MESHING (4NEC2)



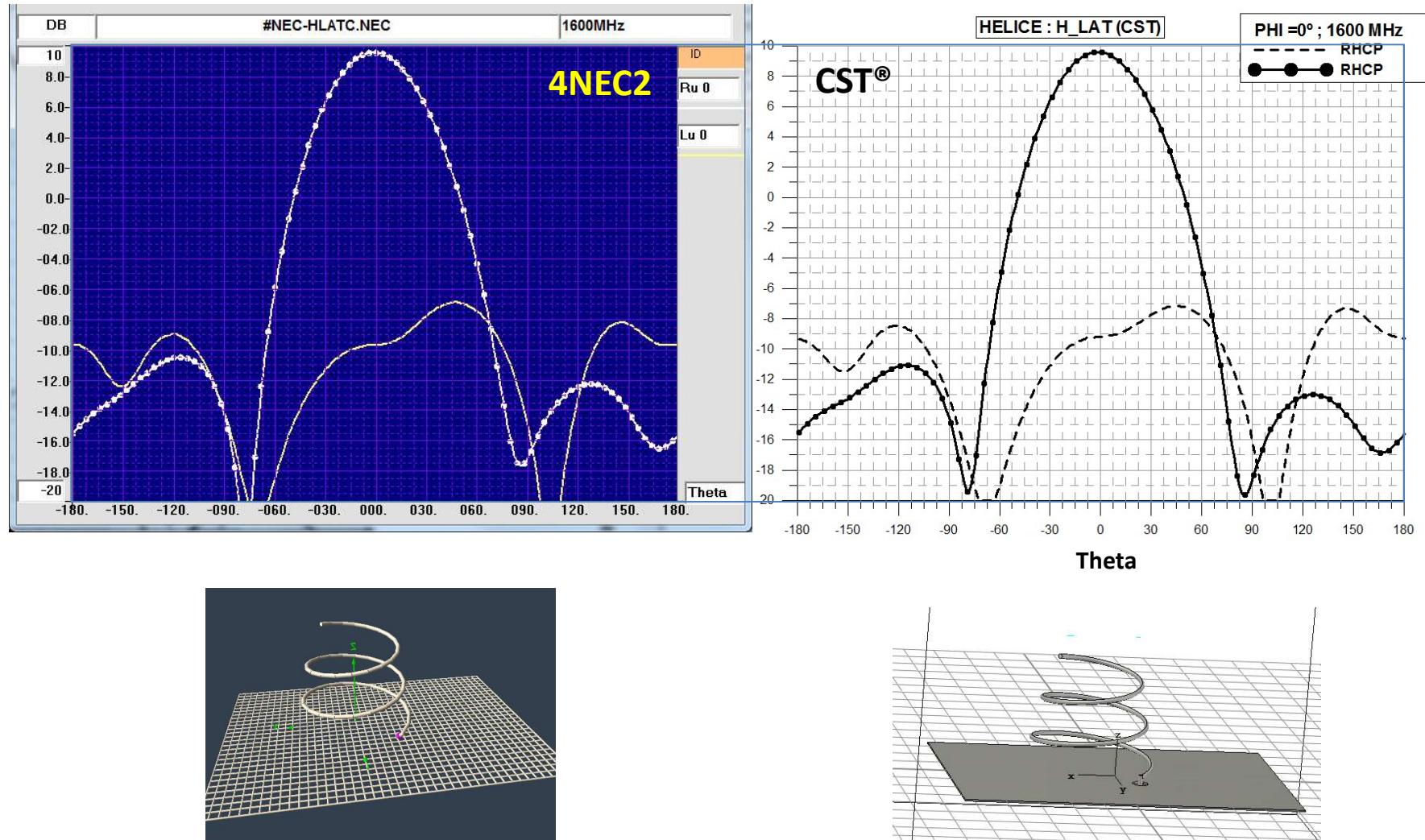
HELIX ALONE : RETURN LOSSES (4NEC2 versus CST)



HELIX PLUS DIELECTRIC PLATE: RETURN LOSSES (4NEC2 versus CST)

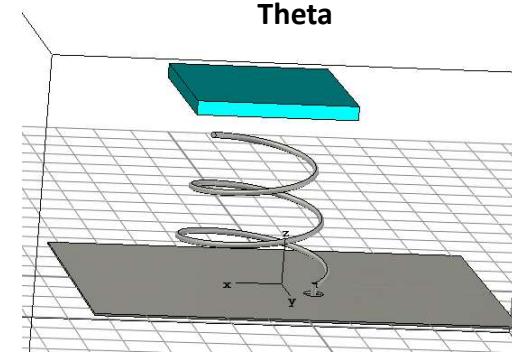
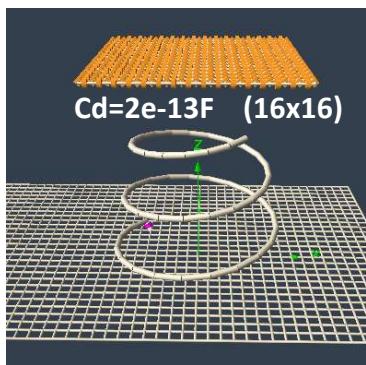
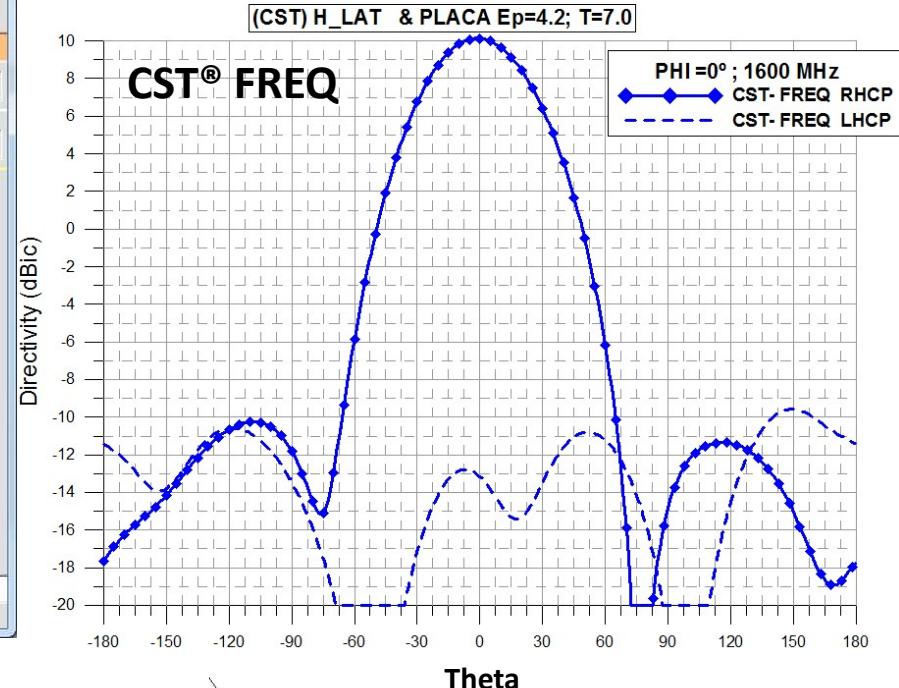
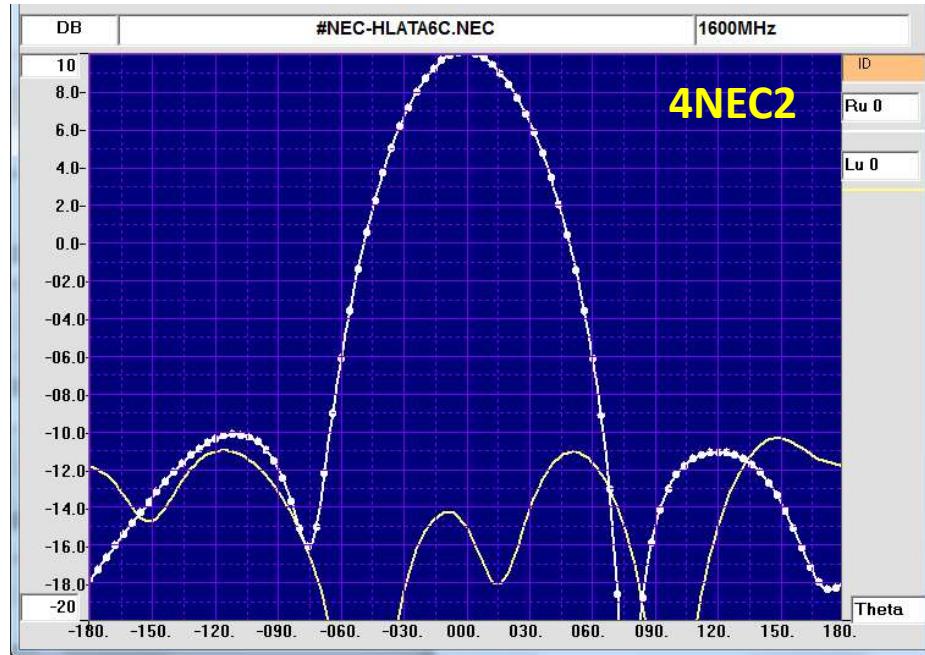


HELIX WITHOUT DIELECTRIC: PATTERN (Phi=00° & 1600MHz)

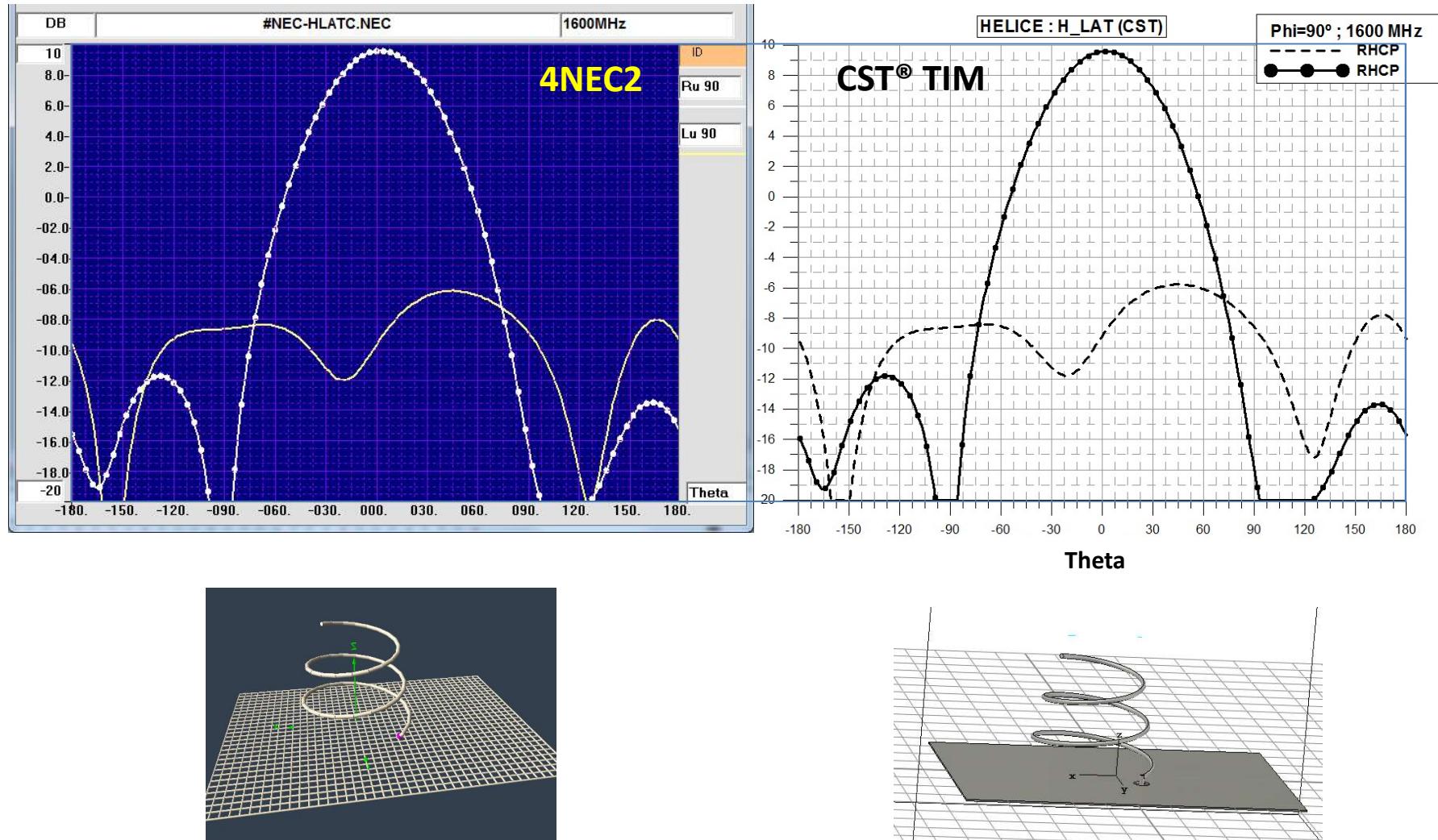


HELIX WITH DIELECTRIC: PATTERN (Phi=00° & 1600MHz)

$$T = 7\text{mm} ; \quad \epsilon' = 4.2$$



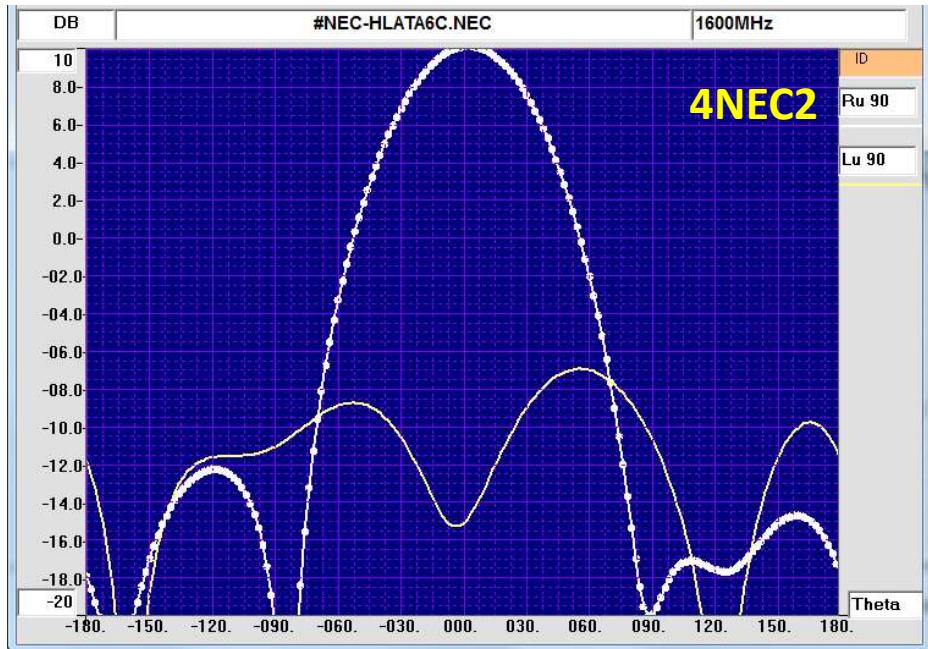
HELIX WITHOUT DIELECTRIC: PATTERN (Phi=90° & 1600MHz)



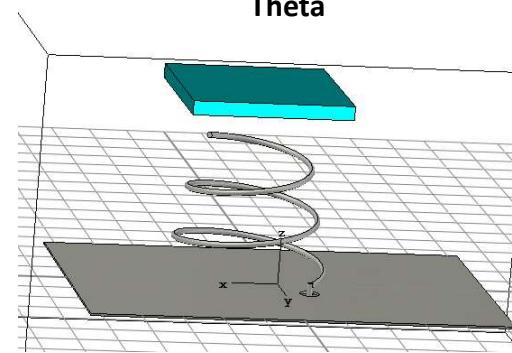
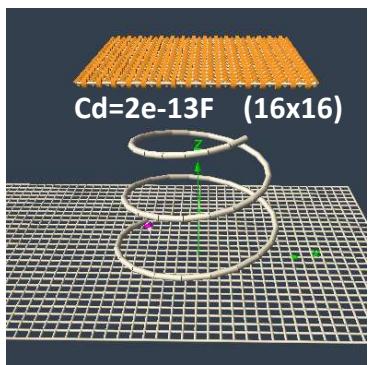
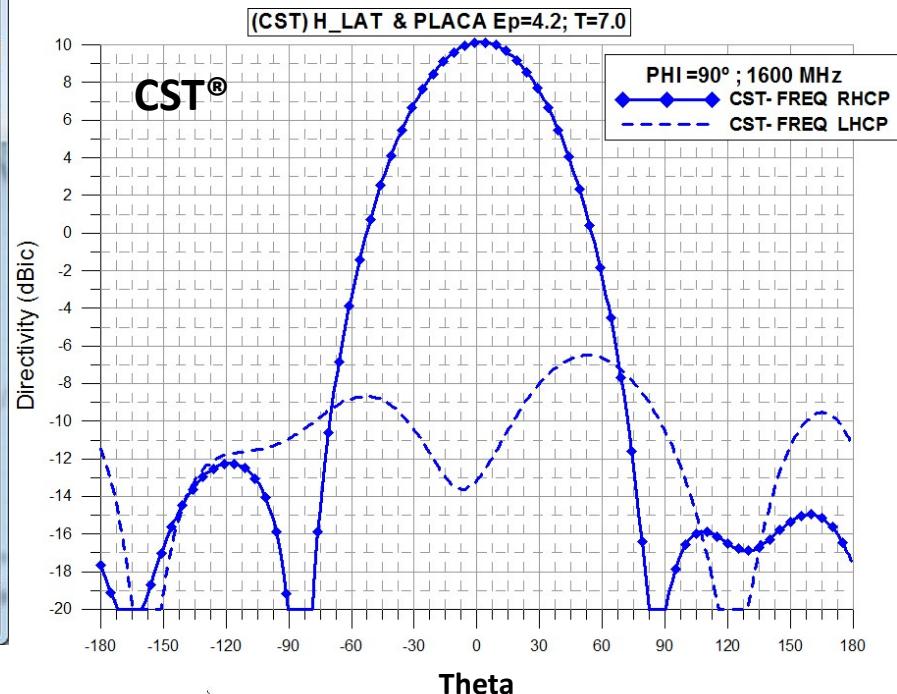
DIELECTRIC FILMS in NEC2

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HELIX WITH DIELECTRIC: PATTERN (Phi=90° & 1600MHz)



$$T = 7\text{mm} ; \quad \epsilon' = 4.2$$

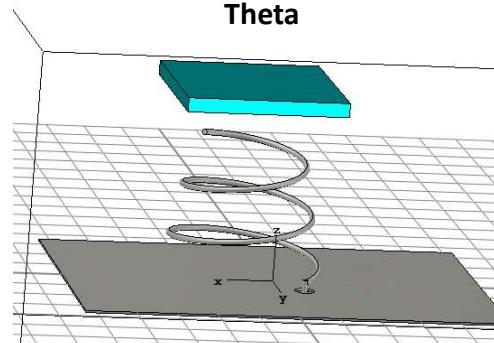
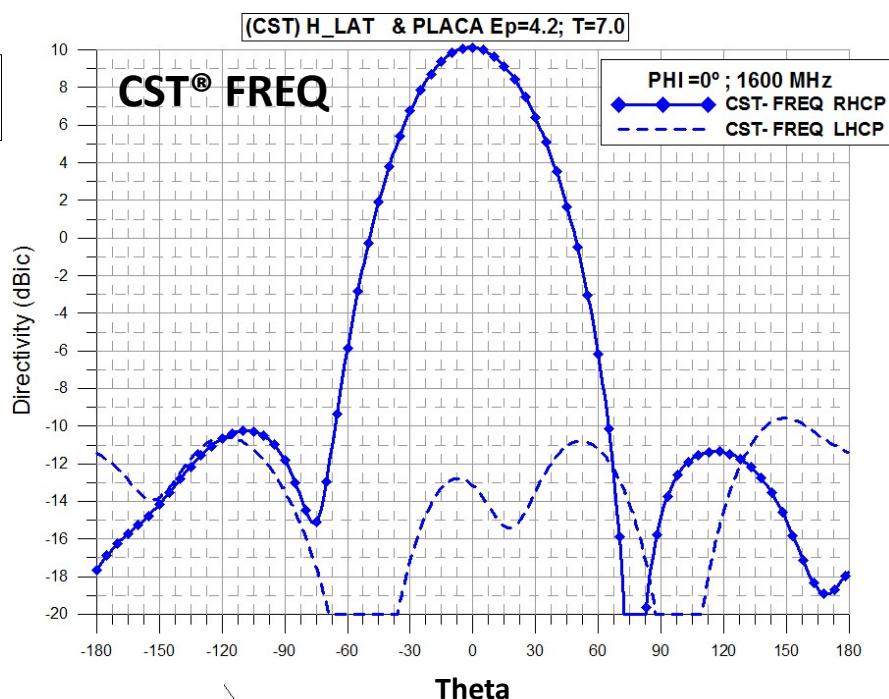
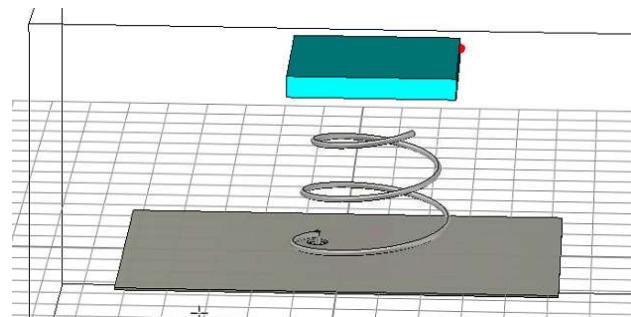
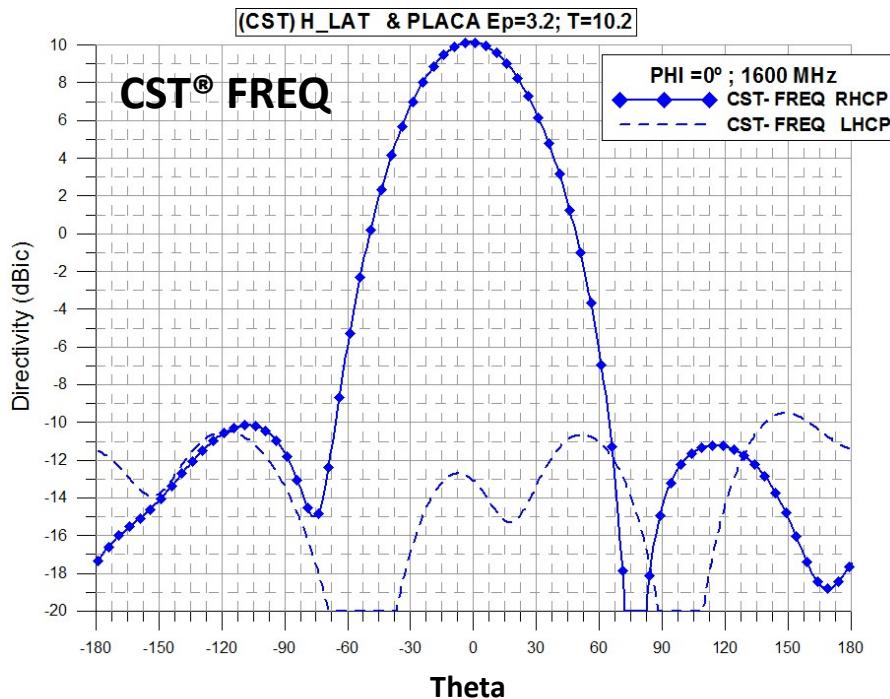


HELIX PLUS DIELECTRIC PLATE : PATTERN (Phi=00° & 1600MHz)

$T = 10.2\text{mm} ; \epsilon' = 3.2$

EQUIVALENT

$T = 7\text{mm} ; \epsilon' = 4.2$



HELIX PLUS DIELECTRIC PLATE : PATTERN (Phi=90° & 1600MHz)

